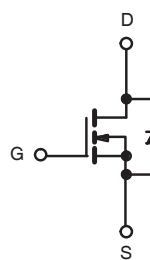
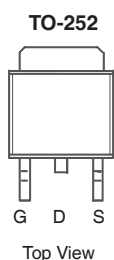


N-Channel 80 V (D-S) Super Junction Power MOSFET

PRODUCT SUMMARY			
$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A) ^c	Q_g (Typ.)
80	0.0029 at $V_{GS} = 10$ V	140	90 nC
	0.0042 at $V_{GS} = 4.5$ V	90	

FEATURES

- DT-Trench Power MOSFET
- 100 % R_g and UIS Tested


RoHS
 COMPLIANT


N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)				
Parameter		Symbol	Limit	Unit
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current ($T_J = 175$ °C) ^b	$T_C = 25$ °C	I_D	140	A
	$T_C = 100$ °C		90 ^a	
Pulsed Drain Current		I_{DM}	560	
Continuous Source Current (Diode Conduction)		I_S	135	
Avalanche Current		I_{AS}	140	
Single Avalanche Energy (Duty Cycle ≤ 1 %)	$L = 0.1$ mH	E_{AS}	300	mJ
Maximum Power Dissipation	$T_C = 25$ °C	P_D	425	W
	$T_C = 125$ °C		150	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	$t \leq 10$ sec	R_{thJA}	10	15	°C/W
	Steady State		20	35	
Maximum Junction-to-Case		R_{thJC}	0.75	1.0	

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

 c. $t \leq 10$ s.

SPECIFICATIONS ($T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	80			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1		3	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 64 V, V _{GS} = 0 V			1	μA
		V _{DS} = 64 V, V _{GS} = 0 V, T _J = 125 °C			10	
		V _{DS} = 64V, V _{GS} = 0 V, T _J = 175 °C			150	
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 10 V, V _{GS} = 10 V	140			A
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 30A		0.0029	0.0035	Ω
		V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.0034	0.0040	
		V _{GS} = 4.5 V, I _D = 20 A		0.0042	0.0055	
Forward Transconductance ^b	g _{fs}	V _{DS} = 64 V, I _D = 30 A		85		S
Dynamic						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 64 V, f = 1 MHz		10050		pF
Output Capacitance	C _{oss}			3340		
Reverse Transfer Capacitance	C _{rss}			460		
Total Gate Charge ^c	Q _g	V _{DS} = 64 V, V _{GS} = 10 V, I _D = 30A		98	120	nC
Gate-Source Charge ^c	Q _{gs}			20		
Gate-Drain Charge ^c	Q _{gd}			30		
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = 64 V, R _L = 0.6 Ω I _D ≅ 30 A, V _{GEN} = 10 V, R _g = 2.5 Ω		10	20	ns
Rise Time ^c	t _r			18	25	
Turn-Off Delay Time ^c	t _{d(off)}			55	80	
Fall Time ^c	t _f			15	22	
Source-Drain Diode Ratings and Characteristics (T _C = 25 °C)						
Pulsed Current	I _{SM}				560	A
Diode Forward Voltage	V _{SD}	I _F = 20 A, V _{GS} = 0 V		0.8	1.5	V
Reverse Recovery Time	t _{rr}	I _F = 30 A, di/dt = 100 A/μs		125	196	ns

Notes:

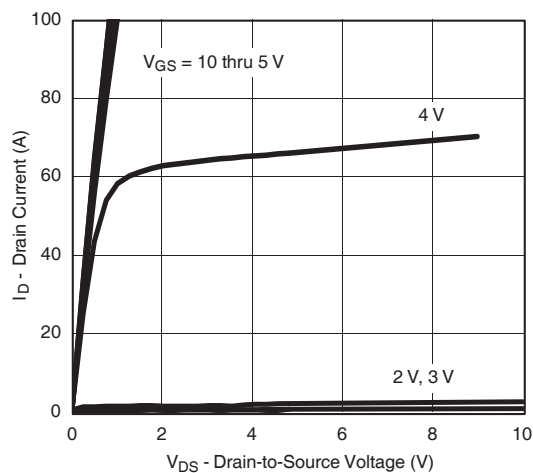
a. For design aid only; not subject to production testing.

 b. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

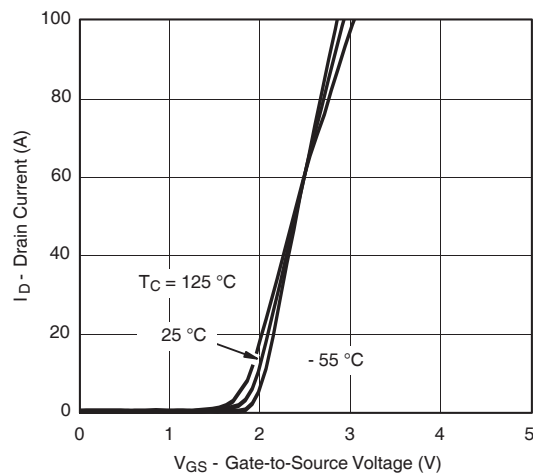
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

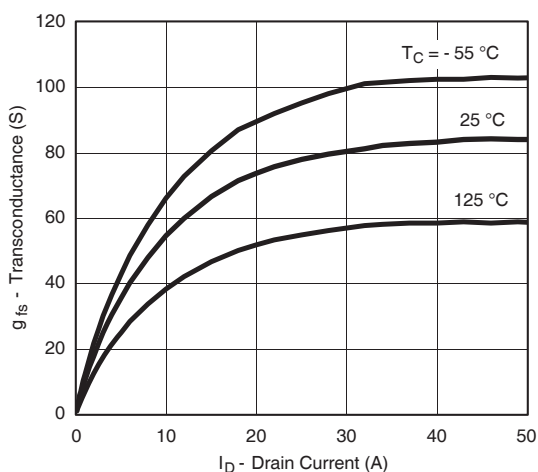
TYPICAL CHARACTERISTICS (25 °C unless noted)



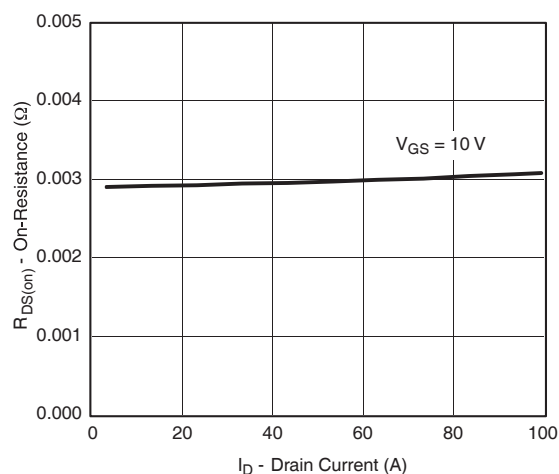
Output Characteristics



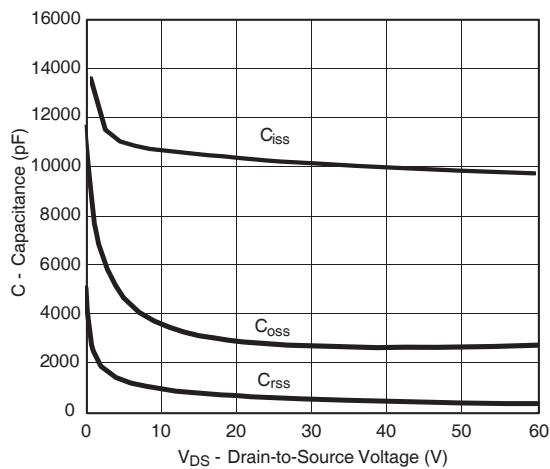
Transfer Characteristics



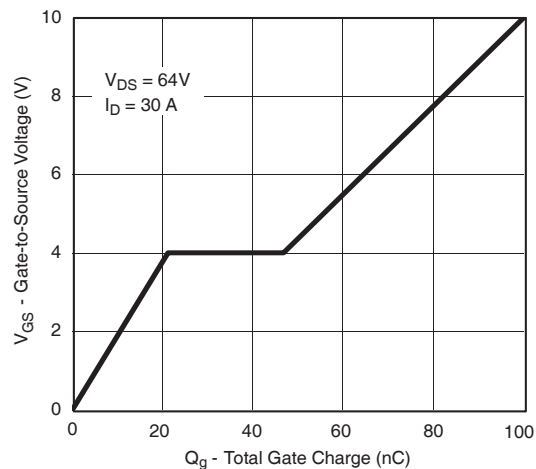
Transconductance



On-Resistance vs. Drain Current

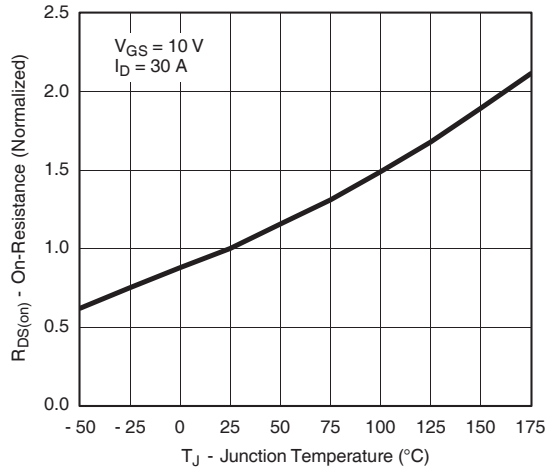


Capacitance

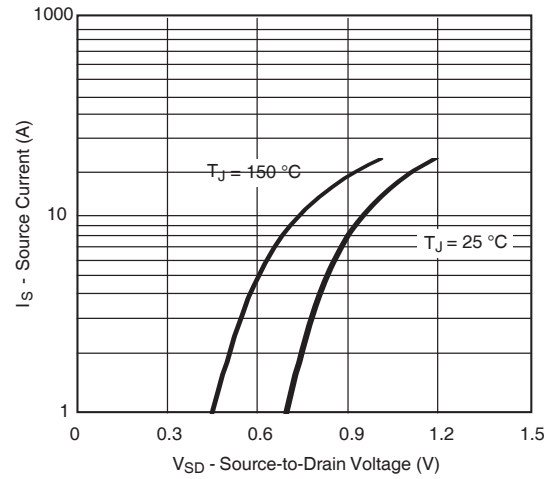


Gate Charge

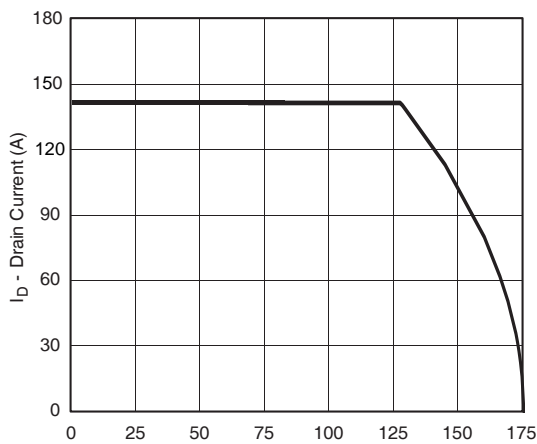
TYPICAL CHARACTERISTICS (25 °C unless noted)



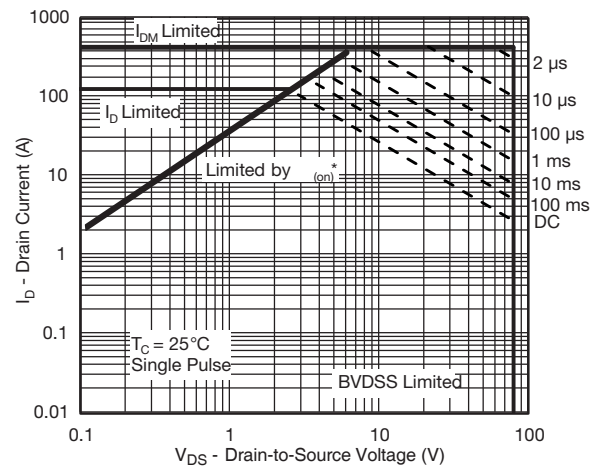
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



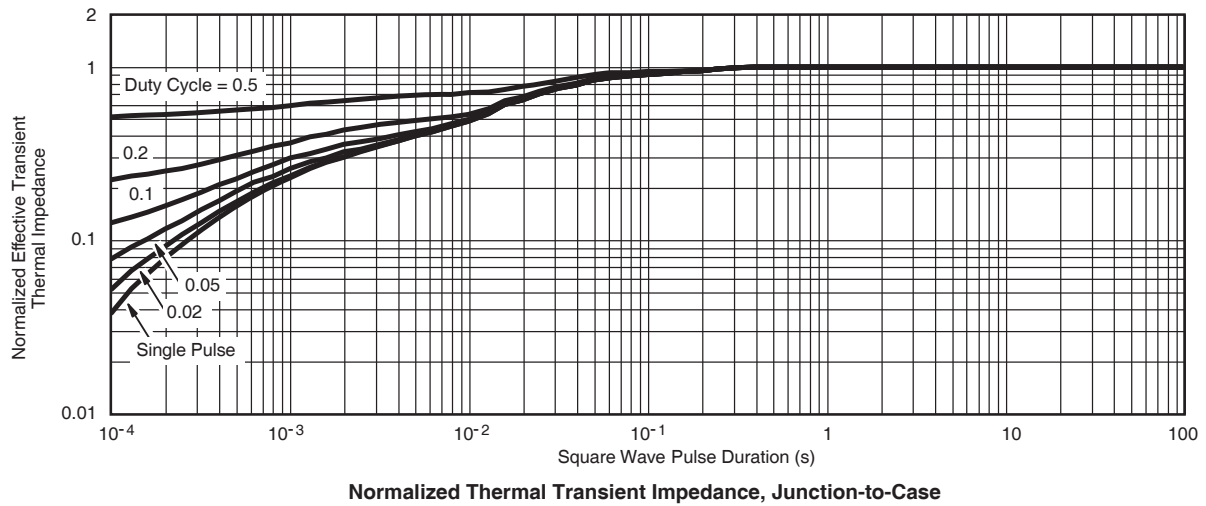
Maximum Drain Current vs. Ambient Temperature



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area

THERMAL RATINGS



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